


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 19 December 2018 [Approved: 10 March 2023, 14:11 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	2.01%	Elemental silicon	7440-21-3	100%
			Carbon black	1333-86-4	1%
			Magnesium hydroxide	1309-42-8	5%
Encapsulation	EP (Epoxy resin)	57.27%	resin	9003-35-4	5%
			Silica	7631-86-9	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.37%	Amorphous silica	60676-86-0	74%
			COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	3.07%	Tin elemental	7440-31-5	100%
			COPPER, ELEMENTAL	7440-50-8	0.168%
Leadframe	Nickel and Nickel alloys	37.28%	SILVER, ELEMENTAL	7440-22-4	1.196%
			Nickel zinc ferrate REACH Article 67 Exemption	12645-50-0	98.636%

Attached parts list

Part number	Part name
SOT-523	Diode/Transistor SMD